

# **600V Super-Junction Power MOSFET**

### FEATURES

- Very low FOM R<sub>DS(on)</sub>×Q<sub>g</sub>
- 100% avalanche tested
- RoHS compliant

## **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

TO-220 GDS	TO-220F GDS	T0-251 G D S	TO-252
RoHS	TO-262 GDS	TO-263 GDS	

Device Marking and Package Information						
Device	TPP60R350C	TPA60R350C	TPU60R350C	TPD60R350C	TPC60R350C	TPB60R350C
Package	TO-220	TO-220F	TO-251	TO-252	TO-262	TO-263
Marking	Marking 60R350C 60R350C 60R350C 60R350C 60R350C 60R350C					

Absolute Maximum Ratings $T_c = 25^{\circ}C$ , unless otherwise noted					
		Value			
Parameter	Symbol	TO-220, TO-251, TO-252 TO-262, TO-263	TO-220F	Unit	
Drain-Source Voltage ( $V_{GS} = 0V$ )	V <sub>DSS</sub>	600		V	
Continuous Drain Current	I <sub>D</sub>	11		А	
Pulsed Drain Current (note1)	I <sub>DM</sub>	33		A	
Gate-Source Voltage	V <sub>GSS</sub>	±30		V	
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	211		mJ	
Avalanche Current (note1)	I <sub>AR</sub>	1.6		A	
Repetitive Avalanche Energy (note1)	E <sub>AR</sub>	0.32		mJ	
Power Dissipation ( $T_c = 25^{\circ}C$ )	P <sub>D</sub>	78	31.3	W	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150		°C	

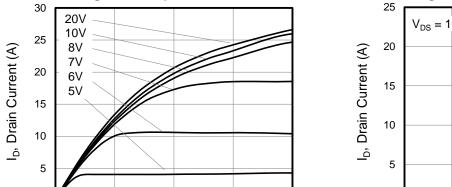
Thermal Resistance					
		Value			
Parameter	Symbol	TO-220, TO-251, TO-252 TO-262, TO-263	TO-220F	Unit	
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	1.6	4.0	•C/W	
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	62	80	°C/W	



<b>Specifications</b> $T_J = 25^{\circ}C$ , ur				Value		
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static		<u> </u>		1	1 1	
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250µA	600			V
		$V_{DS} = 600V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 150°C			100	μA
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 30 V$			±100	nA
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2.5		4	V
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 5.5A		0.30	0.35	Ω
Forward Transconductance (Note3)	<b>g</b> <sub>fs</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 5.5A		7.8		S
Dynamic		•				
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 50V, f = 1.0MHz		901		
Output Capacitance	C <sub>oss</sub>			50		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			5.5		
Total Gate Charge	$Q_{g}$			21		nC
Gate-Source Charge	$Q_gs$	$V_{DD} = 480V, I_{D} = 11A, V_{GS} = 10V$		4.5		
Gate-Drain Charge	$Q_{gd}$	55		7		
Turn-on Delay Time	t <sub>d(on)</sub>			41		
Turn-on Rise Time	t <sub>r</sub>	V <sub>DD</sub> = 400V, I <sub>D</sub> = 11A,		20		20
Turn-off Delay Time	t <sub>d(off)</sub>	$R_{G} = 25\Omega$		123		ns
Turn-off Fall Time	t <sub>f</sub>			6.4		
Drain-Source Body Diode Characteris	stics					
Continuous Body Diode Current	۱ <sub>s</sub>	T - 25%			9.2	۸
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25°C			29	A
Body Diode Voltage	$V_{SD}$	$T_J = 25^{\circ}C, I_{SD} = 11A, V_{GS} = 0V$		0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>			280		ns
Reverse Recovery Charge	Q <sub>rr</sub>	V <sub>R</sub> = 480V, I <sub>F</sub> = I <sub>S</sub> , di <sub>F</sub> /dt = 100A/µs		2.8		μC
Peak Reverse Recovery Current	l <sub>rrm</sub>			17		А

#### Notes

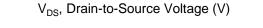
- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2.  $I_{AS}$  = 1.6A,  $V_{DD}$  = 50V,  $R_{G}$  = 25 $\Omega$ , Starting  $T_{J}$  = 25°C
- 3. Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  1%



15

20

**Typical Characteristics**  $T_J = 25^{\circ}C$ , unless otherwise noted



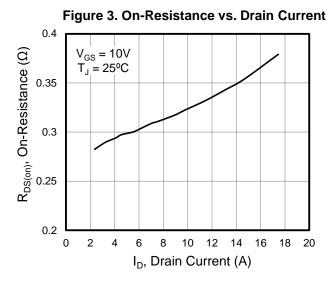
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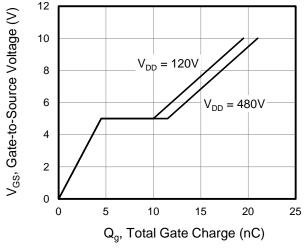
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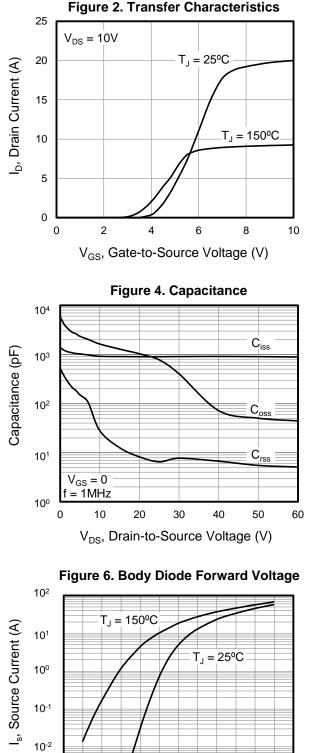
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**Figure 1. Output Characteristics** 









0.8 V<sub>SD</sub>, Source-to-Drain Voltage (V)

1

1.2

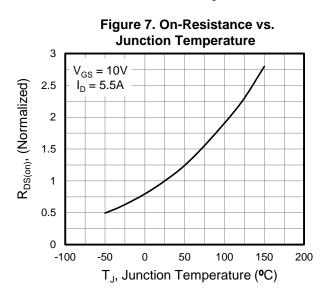
1.4

10<sup>-3</sup> 0.2

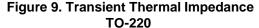
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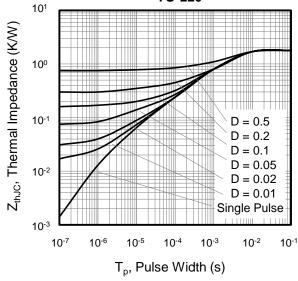
0.6





## **Typical Characteristics** $T_J = 25^{\circ}C$ , unless otherwise noted





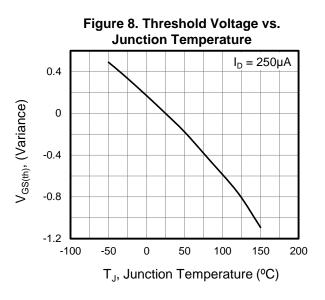


Figure 10. Transient Thermal Impedance TO-220F

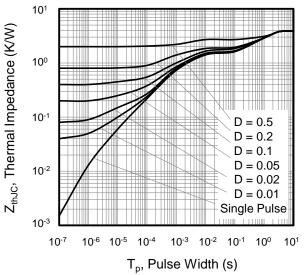


Figure A: Gate Charge Test Circuit and Waveform

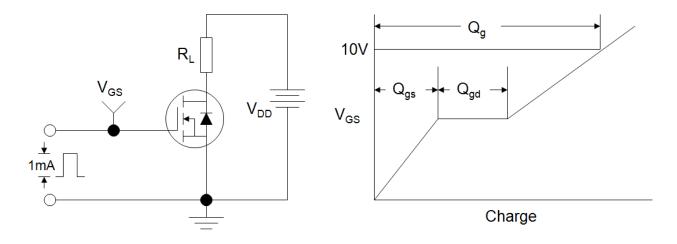


Figure B: Resistive Switching Test Circuit and Waveform

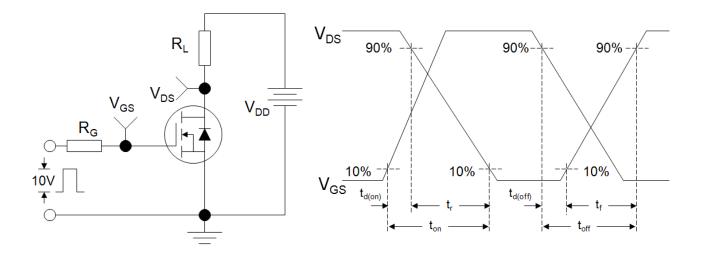
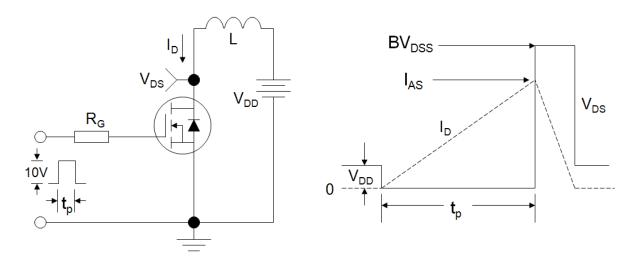
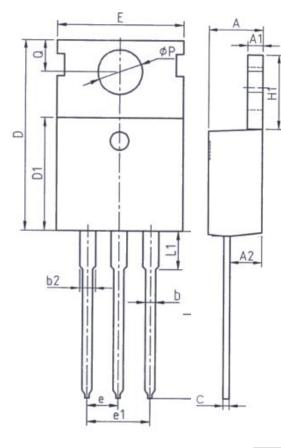


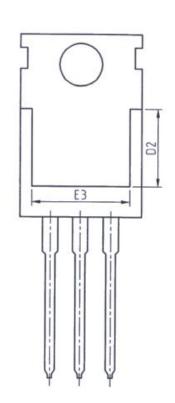
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





**TO-220** 

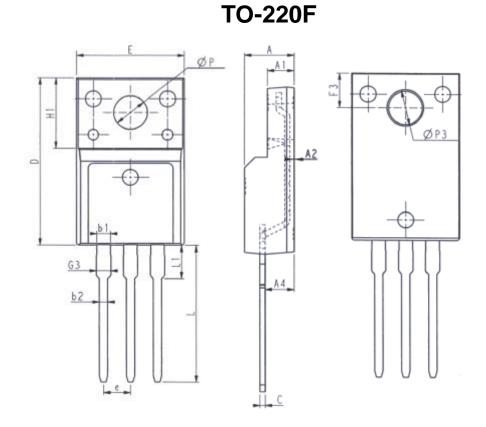




Unit: mm			
Symbol	Min.	Max.	
Α	4.37	4.77	
A1	1.25	1.45	
A2	2.20	2.60	
b	0.70	0.95	
b2	1.17	1.47	
С	0.40	0.65	
D	15.10	16. 10	
D1	8.80	9.40	
D2	5.50	-	

Unit: mm				
Symbol	Min.	Max.		
E	9.70	10. 30		
E3	7.00	-		
e	2. 54BSC			
e1	5. 08	BBSC		
H1	6. 25	6.85		
L	12.75	13.80		
L1	- 3.40			
Р	3. 40	3.80		
Q	2.60	3.00		



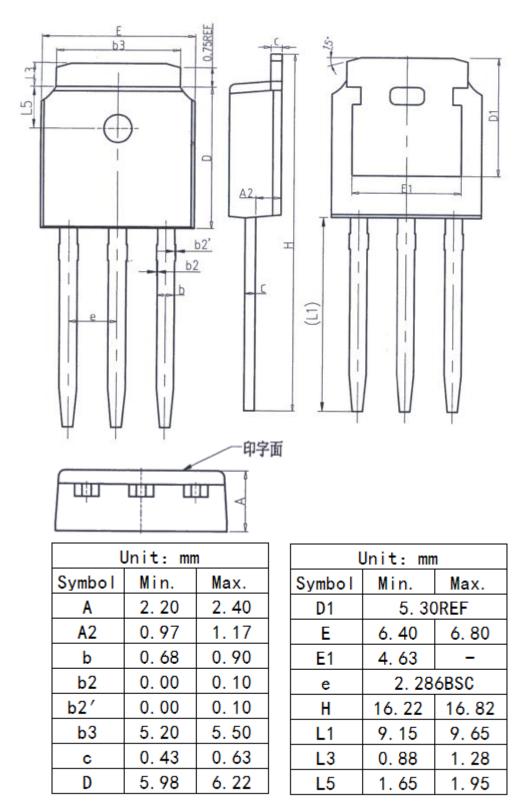


l	Unit: mm			Jnit: mn	n
Symbol	Min.	Max.	Symbol	Min.	Max.
E	9.96	10.36	L	12. 68	13. 28
Α	4.50	4.90	L1	2.93	3.13
A1	2.34	2.74	Р	3.03	3. 38
A2	0.30	0.60	P3	3. 15	3.65
A4	2.56	2.96	F3	3. 15	3. 45
с	0.40	0.65	G3	1.25	1.55
D	15. 57	16. 17	b1	1.18	1.43
H1	6. 70	OREF	b2	0.70	0.95
e	2. 54	4BSC			

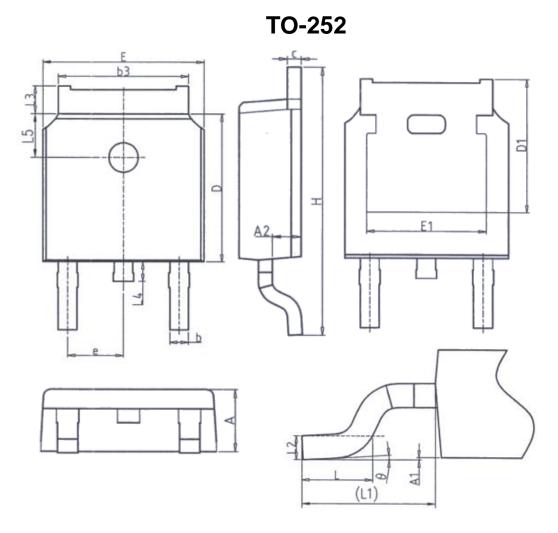
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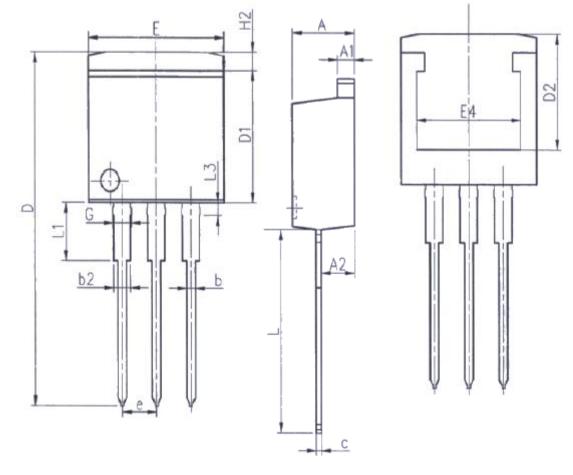


Unit: mm				
Symbol	Min.	Max.		
Α	2.20	2.40		
A1	0.00	0.20		
A2	0.97	1.17		
b	0.68	0.90		
b3	5.20	5.50		
с	0.43	0.63		
D	5.98	6. 22		
D1	D1 5. 30REF			
E	6.40	6.80		
E1	4.63	-		

Unit: mm				
Symbol	Min.	Max.		
е	2. 28	6BSC		
Н	9.40	10.50		
L	1.38	1.75		
L1	2. 90REF			
L2	0, 51	BSC		
L3	0.88	1.28		
L4	- 1.00			
L5	1.65 1.95			
θ	0°	8°		



**TO-262** 

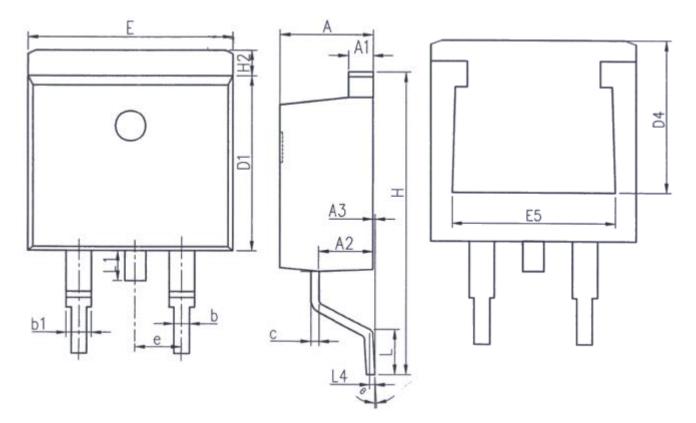


Unit: mm				
Symbol	Min.	Max.		
Α	4. 37	4.77		
A1	1.22	1.42		
A2	2.47	2.87		
b	0.70	0.97		
b2	1.17	1.42		
с	0. 28	0.53		
D	23.20	24. 02		
D1	8. 38	8.90		
D2	6.00	-		

Unit: mm					
Symbol	Min.	Max.			
E	9.90	10.39			
E4	7.30	-			
e	2.54BSC				
G	1. 25	1.50			
H2	-	1.31			
L	13.34	14. 10			
L1	3.30	4.06			
L3	0.95	1.15			



TO-263



Unit: mm			Unit: mm		
Symbol	Min.	Max.	Symbol	Min.	Max.
Α	4. 37	4. 77	E	9.86	10.36
A1	1.22	1.42	E5	7.06	-
A2	2.49	2.89	e	2. 54BSC	
A3	0.00	0. 25	Н	14. 70	15.50
b	0.70	0.96	H2	1.07	1.47
b1	1.17	1.47	L	2.00	2.60
с	0.30	0.53	L1	1.40	1.70
D1	8.50	8.90	L4	0. 25BSC	
D4	6.60	-	θ	0°	<b>9</b> °



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